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# Acreeo Capabilities

## Silicon Technology

Complete line for fabrication of Silicon MOS devices for special applications like

- sensors
- nano-device research or material development

### Key equipment

- Si/SiGe epitaxy tool
- Stepper lithography
- Rapid Thermal Annealing and state of the art multi chamber tool for etching of poly-Si, dielectrics and metals.

## MEMS Technology

Fabrication resources for both surface and bulk micro-machining in Silicon, quartz and glass.

### Key equipment

- Wafer bonder
- Mask aligner for contact lithography and RIE tools for deep etching of Si and SiO<sub>2</sub>.

## Post Processing

Enables further steps towards system construction. Devices fabricated and tested on wafer level can be separately mounted as parts of the systems.

### Key equipment

- dice saws
- wafer cleaving tool
- wire bonders
- flipchip bonder

## Measurement Laboratories

Electrum Laboratory offers a very wide spectrum of analytical equipment for both material characterizations and electrical measurement of components.

Examples of available analytical methods

- microscopy (optical, SEM and AFM)
- spectroscopy (SIMS) or diffraction (XRD)

For electrical characterization of components on wafer level automatic probes stations are available together with different apparatus for both DC and high frequency measurements.

-- SotirisFragkiskos - 05-Sep-2011

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